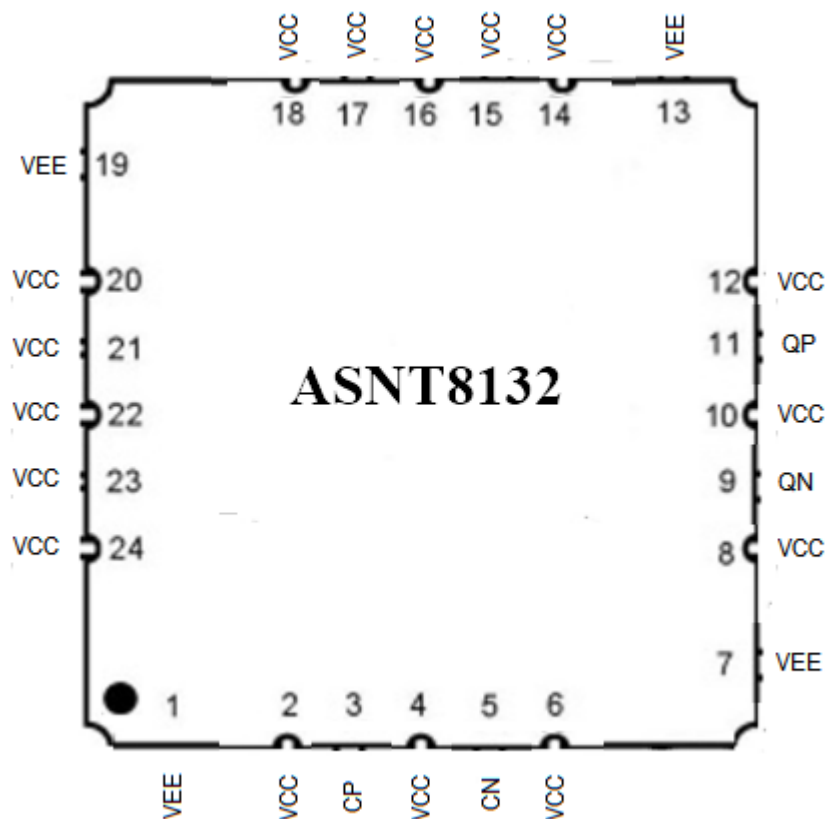




ASNT8132-KHC DC-54GHz Broadband Clock Divider by 2

- High speed broadband clock divider by 2
- Exhibits low jitter and limited temperature variation over industrial temperature range
- Fully differential CML input interface
- Fully differential CML output interface with 400mV single-ended swing
- Single +3.3V or -3.3V power supply
- Power consumption: 630mW
- Fabricated in SiGe for high performance, yield, and reliability
- Custom CQFN 24-pin package



DESCRIPTION

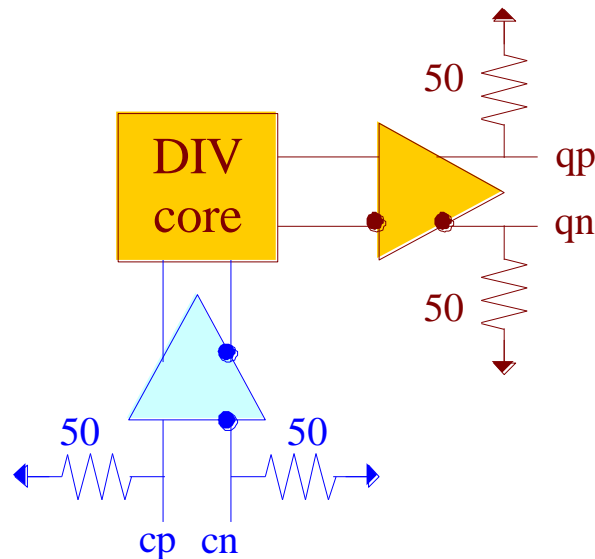


Fig. 1. Functional Block Diagram

The temperature stable ASNT8132-KHC SiGe IC provides broadband clock divide-by-2 functionality, and is intended for use in high-speed measurement / test equipment. The IC shown in Fig. 1 can process a high-speed clock input signal cp/cn and deliver a high-speed clock output signal qp/qn with 50% duty cycle.

The part's I/O's support the CML logic interface with on chip 50 Ω termination to vcc and may be used differentially, AC/DC coupled, single-ended, or in any combination (see also POWER SUPPLY CONFIGURATION). In the DC-coupling mode, the input signal's common mode voltage should comply with the specifications shown in ELECTRICAL CHARACTERISTICS. In the AC-coupling mode, the input termination provides the required common mode voltage automatically. The differential DC signaling mode is recommended for optimal performance.

POWER SUPPLY CONFIGURATION

The part can operate with either a negative supply (vcc = 0.0V = ground and vee = -3.3V), or a positive supply (vcc = +3.3V and vee = 0.0V = ground). In case of a positive supply, all I/Os need AC termination when connected to any devices with 50 Ω termination to ground. Different PCB layouts will be needed for each different power supply combination.

All the characteristics detailed below assume vcc = 0.0V and vee = -3.3V.



ABSOLUTE MAXIMUM RATINGS

Caution: Exceeding the absolute maximum ratings shown in Table 1 may cause damage to this product and/or lead to reduced reliability. Functional performance is specified over the recommended operating conditions for power supply and temperature only. AC and DC device characteristics at or beyond the absolute maximum ratings are not assumed or implied. All min and max voltage limits are referenced to ground.

Table 1. Absolute Maximum Ratings

Parameter	Min	Max	Units
Supply Voltage (vee)		-3.6	V
Power Consumption		0.36	W
RF Input Voltage Swing (SE)		1.0	V
Case Temperature		+90	°C
Storage Temperature	-40	+100	°C
Operational Humidity	10	98	%
Storage Humidity	10	98	%

TERMINAL FUNCTIONS

TERMINAL			DESCRIPTION
Name	No.	Type	
High-Speed I/Os			
cp	3	CML input	Differential clock inputs with internal SE 50Ω termination to VCC
cn	5		
qp	11	CML output	Differential clock outputs with internal SE 50Ω termination to VCC. Require external SE 50Ω termination to VCC
qn	9		
Supply and Termination Voltages			
Name	Description		Pin Number
vcc	Positive power supply (+3.3V or 0)		2, 4, 6, 8, 10, 12, 14, 15, 16, 17, 18, 20, 21, 22, 23, 24
vee	Negative power supply (0V or -3.3V)		1, 7, 13, 19



ELECTRICAL CHARACTERISTICS

PARAMETER	MIN	TYP	MAX	UNIT	COMMENTS
General Parameters					
vee	-3.1	-3.3	-3.5	V	±6%
vcc		0.0		V	External ground
Ivee		190		mA	
Power consumption		630		mW	
Junction temperature	-40	25	125	°C	
HS Input Clock (cp/cn)					
Frequency	DC		54	GHz	
Swing	0.2		1.0	V	Differential or SE, p-p
CM Voltage Level	vcc-0.8		vcc	V	Must match for both inputs
HS Output Clock (qp/qn)					
Frequency	DC		27	GHz	
Logic "1" level		vcc		V	
Logic "0" level		vcc-0.4		V	With external 50Ohm DC termination
Rise/Fall times	4	5	7	ps	20%-80%
Output Jitter			1	ps	Peak-to-peak
Duty cycle	45	50	55	%	

PACKAGE INFORMATION

The chip die is housed in a custom 24-pin CQFN package shown in **Error! Reference source not found.** The package provides a center heat slug located on its back side to be used for heat dissipation. ADSANTEC recommends for this section to be soldered to the vcc plain, which is ground for a negative supply, or power for a positive supply.

The part's identification label is ASNT8132-KHC. The first 8 characters of the name before the dash identify the bare die including general circuit family, fabrication technology, specific circuit type, and part version while the 3 characters after the dash represent the package's manufacturer, type, and pin out count.

This device complies with Commission Delegated Directive (EU) 2015/863 of 4 June 2015 amending Annex II to Directive 2011/65/EU of the European Parliament and of the Council as regards the list of restricted substances (Text with EEA relevance) on the restriction of the use of certain hazardous substances in electrical and electronics equipment (RoHS Directive) in accordance with the definitions set forth in the directives for all ten substances.

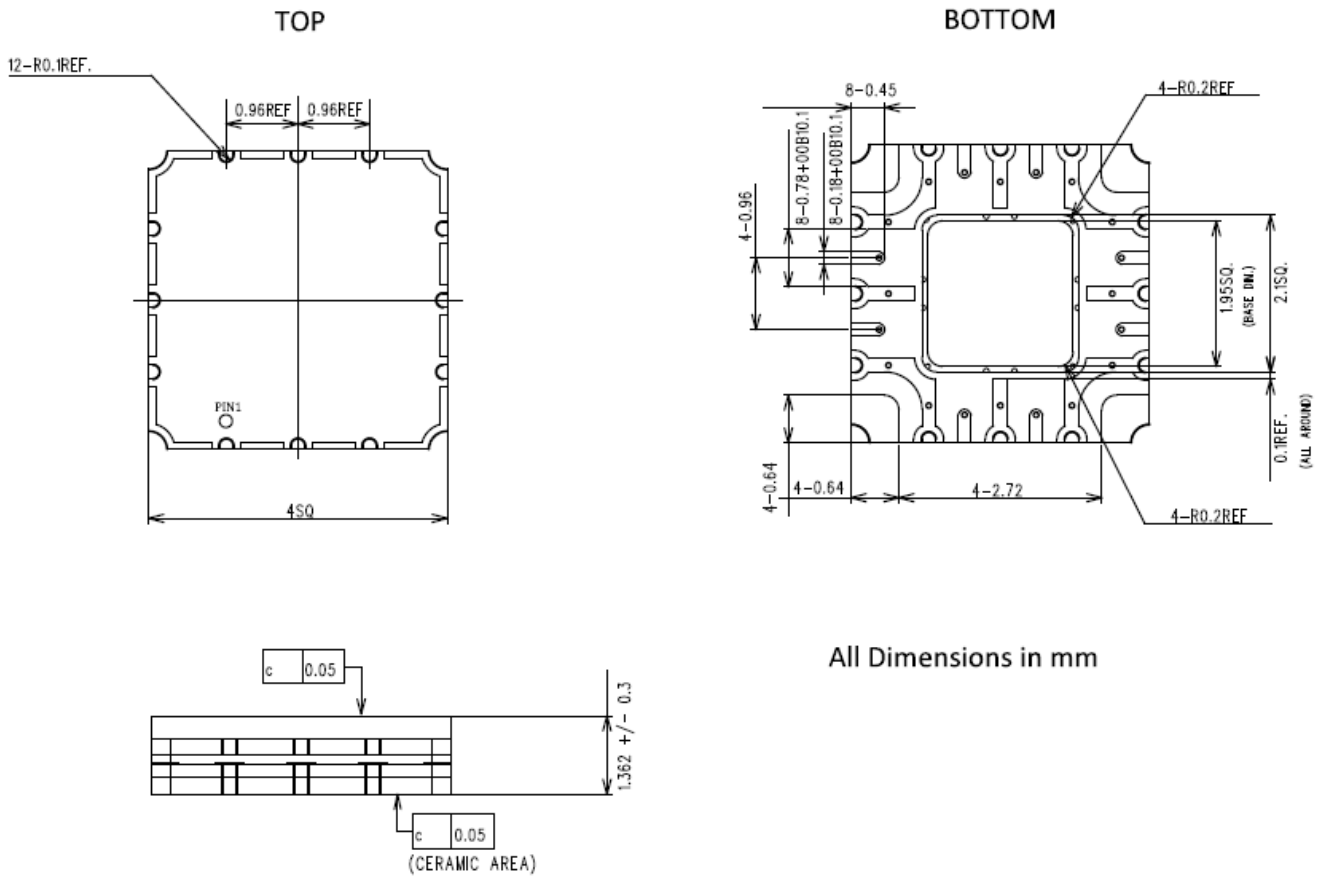


Fig. 2. CQFN 24-Pin Package Drawing (All Dimensions in mm)

REVISION HISTORY

Revision	Date	Changes
1.0.3	04-2023	Updated Package Drawing
1.0.2	11-2021	First release